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Dear Readers,



within PolyIC many forces are mobilised to prepare for the Large-area, Organic and Printed Electronics Convention (LOPE-C) in Frankfurt, Germany. This international conference and exhibition is the official annual event of the Organic Electronics Association (OE-A). As last year, it will open up a broad perspective on the developments and the progress in organic electronics: You can't find

this anywhere else in such a compact form.

This newsletter gives you information on PolyIC's presentation at LOPE-C. Further, the newsletter informs you about two funding projects that PolyIC is participating in: POLYTOS and ORICLA. Please read more about this in the section "Projects".

Please read our section "Applications" to learn about a terminal that was produced by PolyIC for a German mail-order business in order to reach innovative customer service. This terminal, produced for marketing purposes, can be seen and tested - this is where we come full circle - at our booth B10 at LOPE-C in Frankfurt.

Last but not least, we would like to point out to you our presentation at SID 2010 in Seattle, WA. We will present our transparent, conductive films.

I wish you an exciting read.

Yours sincerely
Wolfgang Mildner
 Managing Director PolyIC



Preview:

PolyIC is Gold Sponsor of the LOPE-C 2010



Also in 2010 Gold Sponsor PolyIC will be present with talks and seminars at the Large-area, Organic & Printed Electronics Convention (31st May - 2nd June 2010).

At the first day you will have the opportunity to gain inside into the world of "Devices in Organic / Printed RFID" by the seminar given by **Dr Andreas Ullmann** (Chief Technology Analyst).

On the same day within the frame of the business conference **Dr Wolfgang Clemens** (Head of Applications) will give a talk about "Printed Electronics Applications on their way towards market". This talk will start at 4:30 pm.

At the beginning of the second conference day **Mr Wolfgang Mildner** (PolyIC's Managing Director and Chairman of the OE-A) will give a prospect about the development of printed electronics branch. Visit his presentation "Organic and Printed Electronics - Dawn of a new industry" on Tuesday, 1st of June 2010, 9:30 am.

Also on this day **Dr Walter Fix** (Head of Technology) will show details about the high-resolution printing process in his lecture "Roll-to-roll printed electronics" (Start 3:00 pm).

Besides our talks and seminars please do also visit our **booth B10** in the exhibition area of LOPE-C. We will show you different live applications of printed electronics.

Please feel free to test our customer terminal. Get inspired to implement printed electronics into your own products.

Projects:

EU-funded project ORICLA - started in January 2010



The companies and research institutes PolyIC, Evonik Industries, TNO and IMEC have announced the launch of a new EU-sponsored alliance project called ORICLA to advance the development of high-performance printable Radio Frequency Identification (RFID) tags for mass applications. The project started in January 2010 in the

Framework Programme FP7 (IST) by the European Community.

The funding project ORICLA will be the world's benchmark for RFID performance with Organic and Large Area Electronics (OLAE). RFID is an important technology e.g. in logistics, to transmit an identification code by radio waves between a transponder and a reader. The Electronic Product Code "EPC" protocol has been developed for use in high volume RFID logistic applications. EPC tags are widely used today on pallet level, and will later be used for packages and ultimately on item level. The printed tags are nowadays limited in performance and do not support the EPC protocol.

The ORICLA partners will realize new OLAE chip technologies, based on complementary logic with organic and oxide semiconductors and the scaling up on patterning technology that can provide suitable dimensions. This unique combination will lead to demonstration of OLAE chips and tags with EPC-like performance.

sensor elements for the recognition of threshold values of important external parameters such as temperature or moisture. The cluster partners are aiming to complete the first fundamental prototypes after three years. The overall costs for POLYTOS will reach around 15.1 million Euro. The partners own share of the industry costs will be around 7.3 million Euro.

Applications:

Customer Terminal - Service by means of Printed Electronics



Interaction with the reader - in terms of this slogan a leading mail-order group and PolyIC realized a customer terminal, which can be activated by printed electronics, for the Print-Plus Summit in Munich. The catalogue of the mail-order company was tagged with a printed electronic ticket. As soon as the catalogue is placed close to the terminal, the integrated reader is activated and thereupon a movie about the current catalogue will be shown.

This collaboration was another invest of the mail-order group in its innovative

customer service. Therefore the company has been assigned with the "Germany's most customer-oriented service provider award 2010".

Projects:

BMBF-funded project POLYTOS - PolyIC realized temperature sensor



Together with the companies Merck KGaA (consortium leader), BASF SE, SAP AG, Pepperl+Fuchs GmbH, Robert Bosch GmbH as well as the University of Heidelberg, the Technical University of Darmstadt and Mannheim University of Applied Sciences PolyIC

has announced the launch of a new German Federal Ministry of Education & Research (BMBF)-funded alliance project called POLYTOS.

The aim of this project within the framework of the top cluster Rhine-Neckar Forum Organic Electronics is the development of sensor printed boards based on organic electronics components. This incorporates the development of new concepts and manufacturing procedures for printed organic boards with additional functions for applications in the packaging and textiles area. These systems are also called smart labels, smart tags or smart objects. Within the framework of the sub-project "Organic Printed Boards with Sensors", PolyIC is developing organically based integrated printed boards and printable

Preview:

Meet PolyIC at SID 2010 in Seattle



PolyIC will exhibit at SID, International Symposium, Seminar and Exhibition, which will take place in Seattle, USA from May 23rd to 28th, 2010. Poly-

IC's main focus of this exhibition is on transparent conductive films. These films can be used as an alternative to ITO. Fields of application are e.g. touch sensors, displays, EMI and ESD protection or heating elements. You can meet us at our **booth no. 423**.

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